- Self-Calibrates Input Offset Voltage to 40 μV Max
- Low Input Offset Voltage Drift ... 1 μV/°C
- Input Bias Current . . . 1 pA
- Open Loop Gain . . . 120 dB
- Rail-To-Rail Output Voltage Swing
- Stable Driving 1000 pF Capacitive Loads
- Gain Bandwidth Product . . . 4.7 MHz

- Slew Rate . . . 2.5 V/μs
- High Output Drive Capability . . . ±50 mA
- Calibration Time . . . 300 ms
- Characterized From –55°C to 125°C
- Available in Q-Temp Automotive HighRel Automotive Applications Configuration Control / Print Support Qualification to Automotive Standards

## description

The TLC4501 and TLC4502 are the highest precision CMOS single supply rail-to-rail operational amplifiers available today. The input offset voltage is 10  $\mu$ V typical and 40  $\mu$ V maximum. This exceptional precision, combined with a 4.7-MHz bandwidth, 2.5-V/ $\mu$ s slew rate, and 50-mA output drive, is ideal for multiple applications including: data acquisition systems, measurement equipment, industrial control applications, and portable digital scales.

These amplifiers feature *self-calibrating* circuitry which digitally trims the input offset voltage to less than 40  $\mu$ V within the first 300 ms of operation. The offset is then digitally stored in an integrated successive approximation register (SAR). Immediately after the data is stored, the calibration circuitry effectively drops out of the signal path, shuts down, and the device functions as a standard operational amplifier.

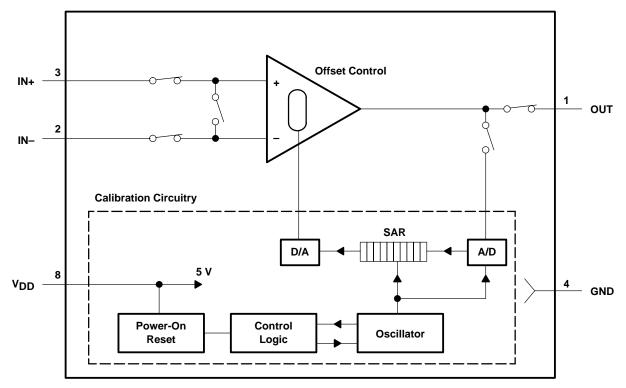


Figure 1. Channel One of the TLC4502



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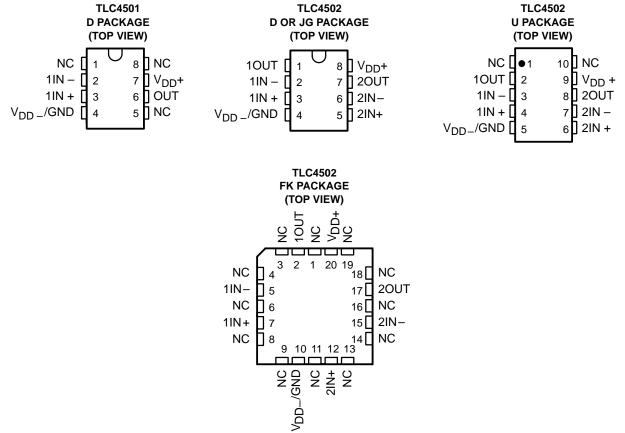
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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## description (continued)

Using this technology eliminates the need for noisy and expensive chopper techniques, laser trimming, and power hungry, split supply bipolar operational amplifiers.



NC - No internal connection

#### **AVAILABLE OPTIONS**

			PACKAGE	DEVICES	
ТА	V <sub>IO</sub> max AT 25°C	SMALL OUTLINE <sup>†</sup> (D)	CHIP CARRIER (FK)	CERAMIC DIP (JG)	CERAMIC FLAT PACK (U)
	40 μV	TLC4501ACD	—	—	—
0°C to 70°C	50 µV	TLC4502ACD	—	—	_
0010700	80 μV	TLC4501CD	—	—	—
	100 μV	TLC4502CD	—	—	—
	40 μV	TLC4501AID	—	—	—
-40°C to 125°C	50 µV	TLC4502AID	—	—	—
-40°C 10 125°C	80 µV	TLC4501ID	—	—	—
	100 μV	TLC4502ID	—	—	—
-40°C to 125°C	50 μV	TLC4502AQD	—	—	—
-40 0 10 1250	100 μV	TLC4502QD	_	_	_
	50 μV	TLC4502AMD	TLC4502AMFKB	TLC4502AMJGB	TLC4502AMUB
–55°C to 125°C	100 μV	TLC4502MD	TLC4502MFKB	TLC4502MJGB	TLC4502MUB

<sup>†</sup>The D package is also available taped and reeled.



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

$\mathbf{O}$ and $\mathbf{O}$ is a here $\mathbf{N}$ (see Nets 4)	
Supply voltage, V <sub>DD+</sub> (see Note 1)	
Differential input voltage, VID (see Note 2)	±7 V
Input voltage range, VI (any input, see Note 1)	0.3 V to 7 V
Input current, I <sub>I</sub> (each input)	±5 mA
Output current, I <sub>O</sub> (each output)	±100 mA
Total current into V <sub>DD+</sub>	±100 mA
Total current out of V <sub>DD</sub> _/GND	±100 mA
Electrostatic discharge (ESD)	> 2 kV
Duration of short-circuit current at (or below) 25°C (see Note 3)	unlimited
Continuous total power dissipation	. See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub> : TLC4502C	0°C to 70°C
TLC4502I	–40°C to 125°C
TLC4502Q	–40°C to 125°C
TLC4502M	–55°C to 125°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C
Case temperature for 60 seconds, T <sub>C</sub> : FK package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to VDD \_/GND.

- 2. Differential voltages are at IN+ with respect to IN-. Excessive current flows when an input is brought below VDD--0.3 V.
- 3. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

DISSIPATION	RATING	TABLE
0.000		

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW
FK	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
JG	1050 mW	8.4 mW/°C	672 mW	546 mW	210 mW
U	675 mW	5.4 mW/°C	432 mW	350 mW	135 mW

## recommended operating conditions

	TLC4502C		TLC4502I		TLC4502Q		TLC4502M		UNIT
	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
Supply voltage, V <sub>DD</sub>	4	6	4	6	4	6	4	6	V
Input voltage range, VI	V <sub>DD-</sub>	V <sub>DD+</sub> – 2.3	V <sub>DD-</sub>	V <sub>DD+</sub> – 2.3	V <sub>DD-</sub>	V <sub>DD+</sub> – 2.3	V <sub>DD-</sub>	V <sub>DD+</sub> – 2.3	V
Common-mode input voltage, VIC	V <sub>DD</sub> -	V <sub>DD+</sub> – 2.3	V <sub>DD</sub> -	V <sub>DD+</sub> – 2.3	V <sub>DD</sub> -	V <sub>DD+</sub> – 2.3	$V_{DD-}$	V <sub>DD+</sub> – 2.3	V
Operating free-air temperature, TA	0	70	-40	125	-40	125	-55	125	°C



## electrical characteristics at specified free-air temperature, V<sub>DD</sub> = 5 V, GND = 0 (unless otherwise noted)

		TEA			<b>-</b> +	TI	_C450xC	:	
	PARAMETER	IES	T CONDITION	NS	TA‡	MIN	TYP	MAX	UNI
				TLC4501		-80	10	80	
\ <i>l</i>		$V_{DD} = \pm 2.5 V,$	$V_{O} = 0,$	TLC4501A	E. III was as	-40	10	40	
VIO	Input offset voltage	$V_{IC} = 0,$		TLC4502	Full range	-100	10	100	μV
				TLC4502A		-50	10	50	
αNIO	Temperature coefficient of input offset voltage				Full range		1		μV/°
li o	Input offset current	$V_{DD} = \pm 2.5 V, V_{O} = 0,$		25°C		1	60	рА	
10	Input offset current				Full range			500	рА
lun.	Input biog ourropt				25°C		1	60	рА
ΙB	Input bias current				Full range			500	PΑ
		I <sub>OH</sub> = - 500 μA	١		25°C		4.99		
Vон	High-level output voltage	I <sub>OH</sub> = – 5 mA		25°C		4.9		V	
		10H 3 111A			Full range	4.7			
		$V_{IC} = 2.5 \text{ V}, \qquad I_{OL} = 500 \mu\text{A}$		A	25°C		0.01		
VOL	OL Low-level output voltage	$V_{IC} = 2.5 V$ , $I_{OL} = 5 mA$			25°C		0.1		V
		$v_{\rm IC} = 2.5 v_{\rm r}$	IOL = 2 IIIA		Full range			0.3	
A. (7)	Large-signal differential voltage	V <sub>IC</sub> = 2.5 V,	$V_0 = 1 V to$	4 V,	25°C	200	1000		\//m
AVD	amplification	$R_L = 1 k\Omega$ ,	See Note 4		Full range	200			V/mV
R <sub>I(D)</sub>	Differential input resistance				25°C		10		kΩ
RL	Input resistance	See Note 4			25°C		10 <sup>12</sup>		Ω
CL	Common-mode input capacitance	f = 10 kHz,	P package		25°C		8		pF
zO	Closed-loop output impedance	A <sub>V</sub> = 10,	f = 100 kHz		25°C		1		Ω
CMRR	Common mode rejection ratio	$V_{IC} = 0$ to 2.7 \	/, Vo = 2.5 \	/,	25°C	90	100		d۵
CIVIRR	Common-mode rejection ratio	$R_{S} = 1 k\Omega$	-		Full range	85			dE
kovr	Supply-voltage rejection ratio		V VI- 0	Noloci	25°C	90	100		dB
<b>k</b> SVR	$(\Delta V_{DD} \pm / \Delta V_{IO})$	V <sub>DD</sub> = 4 V to 6	v, $v$  C = 0,	NO IDAU	Full range	90			dE
					25°C		1	1.5	
	Supply current	$V_{O} = 2.5 V$ , No load		1 LC4501/A	Full range			2	
DD	Supply current			TLC4502/A	25°C		2.5	3.5	mΑ
			TLC450		Full range			4	
VIT(CAL)	Calibration input threshold voltage				Full range	4			V

<sup>†</sup> Full range is 0°C to 70°C. NOTE 4: R<sub>L</sub> and C<sub>L</sub> values are referenced to 2.5 V.



## operating characteristics, $V_{DD} = 5 V$

		TEAT COULD	TIONS	- +	TLC450x	C, TLC4	50xAC		
	PARAMETER	TEST COND	HONS	TA <sup>†</sup>	MIN	TYP	MAX	UNIT	
SR	Slew rate at unity gain	$V_{O} = 0.5 V \text{ to } 2.5 V,$	$C_{1} = 100 \text{ pE}$	25°C	1.5	2.5		V/µs	
SK	Siew fale at unity gain	$VO = 0.5 \ V \ 10 \ 2.5 \ V,$		Full range	1			V/µs	
V	Equivalent input noise voltage	f = 10 Hz		25°C		70			
Vn	Equivalent input noise voitage	f = 1 kHz		25°C		12		nV/√Hz	
VAVAA	Peak-to-peak equivalent input noise	f = 0.1 to 1 Hz		25°C		1		μV	
V <sub>N(PP)</sub>	voltage	f = 0.1 to 10 Hz		25°C		1.5		μv	
In	Equivalent input noise current			25°C		0.6		fA/√Hz	
		$V_{O} = 0.5 V$ to 2.5 V,	A <sub>V</sub> = 1	25°C		0.02%			
THD + N	Total harmonic distortion plus noise	f = 10 kHz, R <sub>I</sub> = 1 kΩ,	A <sub>V</sub> = 10	25°C		0.08%			
		$C_L = 100 \text{ pF}$	A <sub>V</sub> = 100	25°C		0.55%			
	Gain-bandwidth product	f = 10 kHz, C <sub>L</sub> = 100 pF	R <sub>L</sub> = 1 kΩ,	25°C		4.7		MHz	
BOM	Maximum output swing bandwidth	$V_{O(PP)} = 2 V,$ $R_L = 1 k\Omega,$	A <sub>V</sub> = 1, C <sub>L</sub> = 100 pF	25°C		1		MHz	
ts	Settling time	$A_V = -1$ , Step = 0.5 V to 2.5 V,	to 0.1%	25°C		1.6		μs	
'S		$R_{L} = 1 k\Omega,$ $C_{L} = 100 \text{ pF}$		25°C		2.2		μο	
<sup>¢</sup> m	Phase margin at unity gain	$R_L = 1 k\Omega$ ,	C <sub>L</sub> = 100 pF	25°C		74			
	Calibration time			25°C		300		ms	

<sup>†</sup> Full range is 0°C to 70°C. NOTE 4:  $R_L$  and  $C_L$  values are referenced to 2.5 V.



### electrical characteristics at specified free-air temperature, V<sub>DD</sub> = 5 V, GND = 0 (unless otherwise noted)

	DADAMETED	тее			т.†	TLC450xI			UNIT	
	PARAMETER	IES	T CONDITION	12	T <sub>A</sub> †	MIN	TYP	MAX	UNII	
				TLC4501		-80	10	80		
	Input offect veltage	$V_{DD} = \pm 2.5 V,$	V <sub>O</sub> = 0,	TLC4501A	Full ronge	-40	10	40	μV	
VIO	Input offset voltage	$V_{IC} = 0,$		TLC4502	Full range	-100	10	100	μv	
				TLC4502A		-50	10	50		
αNIO	Temperature coefficient of input offset voltage				Full range		1		μV/°0	
		$V_{DD} = \pm 2.5 V,$			25°C		1	60		
lio	Input offset current	$V_{\text{IC}} = 0, \qquad R_{\text{S}} = 50 \ \Omega$		−40°C to 85°C			500	pА		
					Full range			5	nA	
					25°C		1	60		
I <sub>IB</sub>	Input bias current	$V_{DD} = \pm 2.5 \text{ V},$ $V_{IC} = 0,$	$V_{O} = 0,$ R <sub>S</sub> = 50 $\Omega$		-40°C to 85°C			500	рA	
					Full range			10	nA	
		I <sub>OH</sub> = - 500 μA	L.		25°C		4.99			
Vон	High-level output voltage			25°C		4.9		V		
		IOH = - 5 mA			Full range	4.7				
		V <sub>IC</sub> = 2.5 V,	l <sub>OL</sub> = 500 μ.	A	25°C		0.01			
Vol	Low-level output voltage	V <sub>IC</sub> = 2.5 V,	I <sub>OL</sub> = 5 mA		25°C		0.1		V	
		VIC - 2.0 V,	10L = 0 11#1		Full range			0.3		
AVD	Large-signal differential voltage	V <sub>IC</sub> = 2.5 V,	$V_0 = 1 V to$	4 V,	25°C	200	1000		V/m	
	amplification	$R_L = 1 k\Omega$ ,	See Note 4		Full range	200			V/111V	
RI(D)	Differential input resistance				25°C		10		kΩ	
RL	Input resistance	See Note 4			25°C		1012		Ω	
CL	Common-mode input capacitance	f = 10 kHz,	P package		25°C		8		pF	
zO	Closed-loop output impedance	A <sub>V</sub> = 10,	f = 100 kHz		25°C		1		Ω	
CMRR	Common-mode rejection ratio	$V_{IC} = 0$ to 2.7 \	/, V <sub>O</sub> = 2.5 \	/,	25°C	90	100		dB	
OMINI		$R_S = 1 k\Omega$			Full range	85			ub	
ksvr	Supply-voltage rejection ratio	$V_{DD} = 4 V \text{ to } 6$	V = V = 0	No load	25°C	90	100		dB	
NOVR	$(\Delta V_{DD} \pm / \Delta V_{IO})$	•DD = 1 • 80 0	ν, ν <sub>IC</sub> = ο,		Full range	90			40	
				TLC4501/A	25°C		1	1.5		
DD	Supply current	Vo = 2.5 V,	No load		Full range			2	mA	
עט		, and the second	TLC4502/A	25°C		2.5	3.5			
			F		Full range			4		
VIT(CAL)	Calibration input threshold voltage				Full range	4			V	

<sup>†</sup> Full range is  $-40^{\circ}$ C to  $125^{\circ}$ C.

NOTE 4:  $R_L$  and  $C_L$  values are referenced to 2.5 V.



## operating characteristics, $V_{DD} = 5 V$

		TEST COND		- +	TLC450	xI, TLC4	50xAl	UNIT	
	PARAMETER	TEST COND	HONS	TA <sup>†</sup>	MIN	TYP	MAX	UNIT	
SR	Slew rate at unity gain	$V_{O} = 0.5 V \text{ to } 2.5 V,$	Ct = 100 pE	25°C	1.5	2.5		V/µs	
SK	Siew rate at unity gain	$V_{0} = 0.5 \ V \ 10 \ 2.5 \ V,$	CL = 100 pF	Full range	1			V/µs	
V	Equivalent input noise voltage	f = 10 Hz		25°C		70			
Vn	Equivalent input hoise voitage	f = 1 kHz		25°C		12		nV/√Hz	
Vivoo	Peak-to-peak equivalent input noise	f = 0.1 to 1 Hz		25°C		1		μV	
V <sub>N(PP)</sub>	voltage	f = 0.1 to 10 Hz		25°C		1.5		μv	
In	Equivalent input noise current			25°C		0.6		fA/√Hz	
		$V_{O} = 0.5 V$ to 2.5 V,	A <sub>V</sub> = 1	25°C		0.02%			
THD + N	Total harmonic distortion plus noise	f = 10  kHz, $R_I = 1 \text{ k}\Omega,$	A <sub>V</sub> = 10	25°C		0.08%			
		$C_L = 100 \text{ pF}$	A <sub>V</sub> = 100	25°C		0.55%			
	Gain-bandwidth product	f = 10 kHz, C <sub>L</sub> = 100 pF	R <sub>L</sub> = 1 kΩ,	25°C		4.7		MHz	
вом	Maximum output swing bandwidth	$V_{O(PP)} = 2 V,$ $R_L = 1 k\Omega,$	A <sub>V</sub> = 1, C <sub>L</sub> = 100 pF	25°C		1		MHz	
+_	Settling time	$A_V = -1$ , Step = 0.5 V to 2.5 V,	to 0.1%	25°C		1.6		μs	
t <sub>S</sub>		R <sub>L</sub> = 1 kΩ, C <sub>L</sub> = 100 pF	to 0.01%	25°C		2.2		μο	
<sup>¢</sup> m	Phase margin at unity gain	$R_L = 1 k\Omega$ ,	C <sub>L</sub> = 100 pF	25°C		74			
	Calibration time			25°C		300		ms	

<sup>†</sup> Full range is  $-40^{\circ}$ C to  $125^{\circ}$ C. NOTE 4: R<sub>L</sub> and C<sub>L</sub> values are referenced to 2.5 V.



## electrical characteristics at specified free-air temperature, V<sub>DD</sub> = 5 V, GND = 0 (unless otherwise noted)

	PARAMETER	TES		IS	т <sub>А</sub> †	TLC4502Q, TLC4502M			UNIT	
						MIN	TYP	MAX		
Via	Input offect veltoge	$V_{DD} = \pm 2.5 V,$	V <sub>O</sub> = 0,	TLC4502	Full range	-100	10	100	μV	
VIO	Input offset voltage	$V_{IC} = 0,$	R <sub>S</sub> = 50 Ω	TLC4502A	Full range	-50	10	50	μv	
αΛΙΟ	Temperature coefficient of input offset voltage				Full range		1		μV/°C	
lio	Input offset current	$V_{DD} = \pm 2.5 V, V_{O} = 0,$ $V_{IC} = 0, R_{S} = 50 \Omega$		25°C		1	60	nA		
ΙΟ	input onset current			125°C			5			
IIB	Input bias current			25°C		1	60	nA		
чв	input bias current				125°C			10		
		I <sub>OH</sub> = - 500 μA	L .		25°C		4.99			
Vон	High-level output voltage	I <sub>OH</sub> = - 5 mA		25°C		4.9		V		
				Full range	4.7					
		V <sub>IC</sub> = 2.5 V,	l <sub>OL</sub> = 500 μ	A	25°C		0.01			
VOL	Low-level output voltage			25°C		0.1		V		
		V <sub>IC</sub> = 2.5 V,	$I_{OL} = 5 \text{ mA}$		Full range			0.3		
A	Large-signal differential voltage	V <sub>IC</sub> = 2.5 V,	$V_{O} = 1 V to$	4 V,	25°C	200	1000		V/mV	
AVD	amplification	$R_L = 1 k\Omega$ ,	See Note 4		Full range	200			V/IIIV	
R <sub>I(D)</sub>	Differential input resistance				25°C		10		kΩ	
RL	Input resistance	See Note 4			25°C		1012		Ω	
CL	Common-mode input capacitance	f = 10 kHz,	P package		25°C		8		pF	
zO	Closed-loop output impedance	A <sub>V</sub> = 10,	f = 100 kHz		25°C		1		Ω	
		$V_{IC} = 0$ to 2.7 \	/, Vo = 2.5 V	V,	25°C	90	100			
CMRR	Common-mode rejection ratio	$R_{S} = 1 k\Omega$	Ū		Full range	85			dB	
	Supply-voltage rejection ratio	$V_{DD} = 4 V \text{ to } 6$	V, VIC = VD	D /2,	25°C	90	100		40	
<b>k</b> SVR	$(\Delta V_{DD} \pm / \Delta V_{IO})$			Full range	90			dB		
I	Current automation		Nalaad		25°C		2.5	3.5	A	
DD	Supply current	$V_{O} = 2.5 V$ , No load		Full range			4	mA		
VIT(CAL)	Calibration input threshold voltage				Full range	4			V	

<sup>†</sup> Full range is –40°C to 125°C for Q suffix, –55°C to 125°C for M suffix.

NOTE 4: RL and CL values are referenced to 2.5 V.



## operating characteristics, $V_{DD} = 5 V$

PARAMETER		TEST COND	TEST CONDITIONS			TLC4502Q, TLC4502M, TLC4502AQ, TLC4502AM		
					MIN	TYP	MAX	
SR	Slew rate at unity gain	$V_{O} = 0.5 V$ to 2.5 V,	$C_L = 100 \text{ pF}$	25°C	1.5	2.5		V/µs
ÖN	Clow rate at anny gain	See Note 4		Full range	1			V/µs
Vn	Equivalent input noise voltage	f = 10 Hz		25°C		70		nV/√Hz
۷n	Equivalent input noise voitage	f = 1 kHz		25°C		12		nv/vHz
Maria	Peak-to-peak equivalent input noise	f = 0.1 to 1 Hz		25°C		1		
VN(PP)	voltage	f = 0.1 to 10 Hz		25°C	1.5		μV	
In	Equivalent input noise current			25°C		0.6		fA/√Hz
	HD + N Total harmonic distortion plus noise	$V_{O} = 0.5 V \text{ to } 2.5 V,$	A <sub>V</sub> = 1	25°C		0.02%		
THD + N		f = 10  kHz, R <sub>1</sub> = 1 kΩ.	f = 10  kHz, $R_{I} = 1 \text{ k}\Omega,$	A <sub>V</sub> = 10	25°C		0.08%	
		$C_{L} = 100 \text{ pF}$	A <sub>V</sub> = 100	25°C		0.55%		
	Gain-bandwidth product	f = 10 kHz, C <sub>L</sub> = 100 pF	R <sub>L</sub> = 1 kΩ,	25°C		4.7		MHz
ВОМ	Maximum output swing bandwidth	$V_{O(PP)} = 2 V,$ $R_L = 1 k\Omega,$	A <sub>V</sub> = 1, C <sub>L</sub> = 100 pF	25°C		1		MHz
	Settling time	$A_V = -1$ , Step = 0.5 V to 2.5 V,	to 0.1%	25°C	1.6			
t <sub>S</sub>	$\begin{array}{l} R_{L} = 1 \ k\Omega, \\ C_{L} = 100 \ pF \end{array}$	R <sub>L</sub> = 1 kΩ, C <sub>L</sub> = 100 pF	to 0.01%	25°C		2.2		μs
<sup>¢</sup> m	Phase margin at unity gain	R <sub>L</sub> = 1 kΩ,	C <sub>L</sub> = 100 pF	25°C		74		
	Calibration time			25°C		300		ms

<sup>†</sup> Full range is –40°C to 125°C for Q suffix, –55°C to 125°C for M suffix.

NOTE 4: RL and CL values are referenced to 2.5 V.

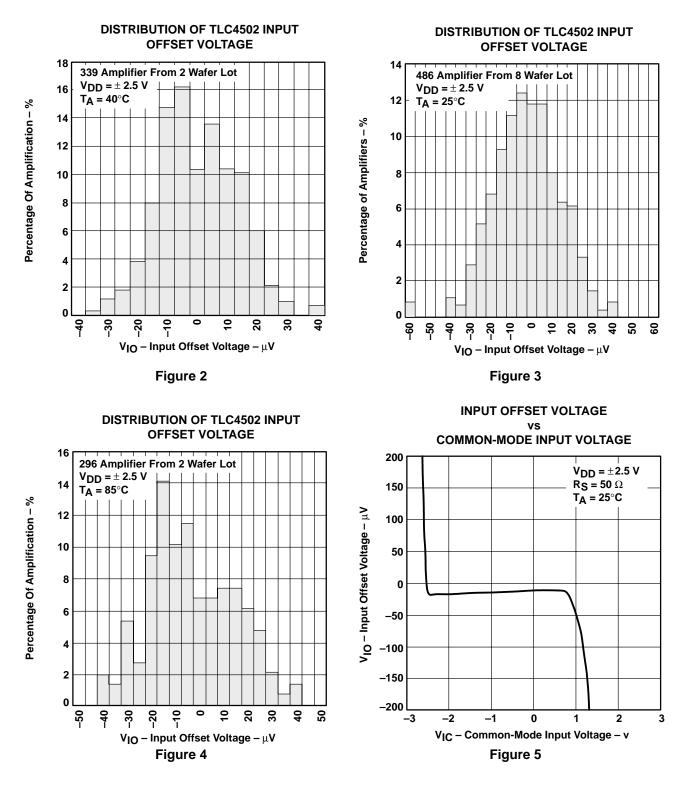


**TYPICAL CHARACTERISTICS** 

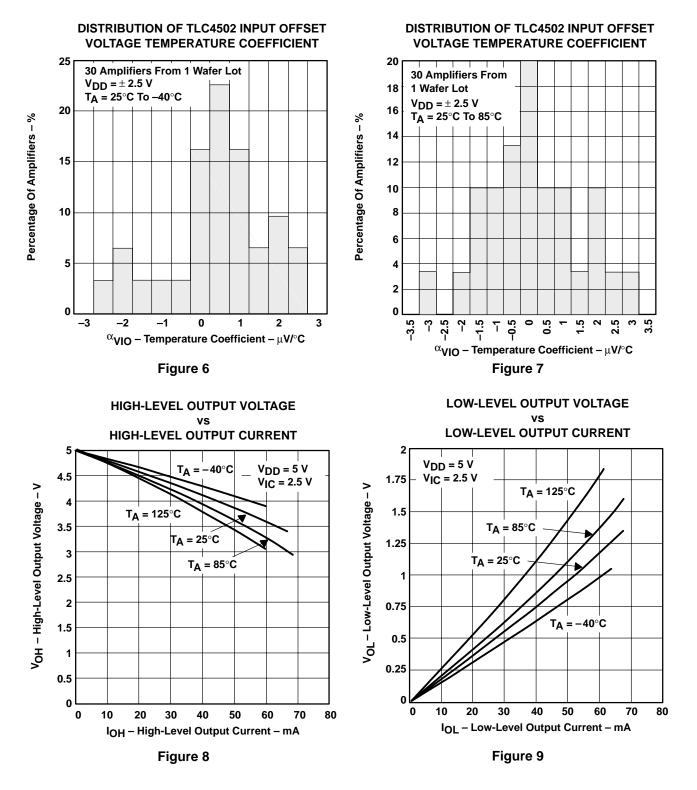
### **Table of Graphs**

			FIGURE
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αVIO	Input offset voltage temperature coefficient	Distribution	6, 7
Vон	High-level output voltage	vs High-level output current	8
VOL	Low-level output voltage	vs Low-level output current	9
VO(PP)	Maximum peak-to-peak output voltage	vs Frequency	10
los	Short-circuit output current	vs Free-air temperature	11
VO	Output voltage	vs Differential input voltage	12
A <sub>VD</sub>	Large-signal differential voltage amplification	vs Free-air temperature vs Frequency	13 14
z <sub>0</sub>	Output impedance	vs Frequency	15
CMRR	Common-mode rejection ratio	vs Frequency vs Free-air temperature	16 17
SR	Slew rate	vs Load capacitance vs Free-air temperature	18 19
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	Calibration time at $-40^{\circ}$ C		31
	Calibration time at 25°C		32
	Calibration time at 85°C		33
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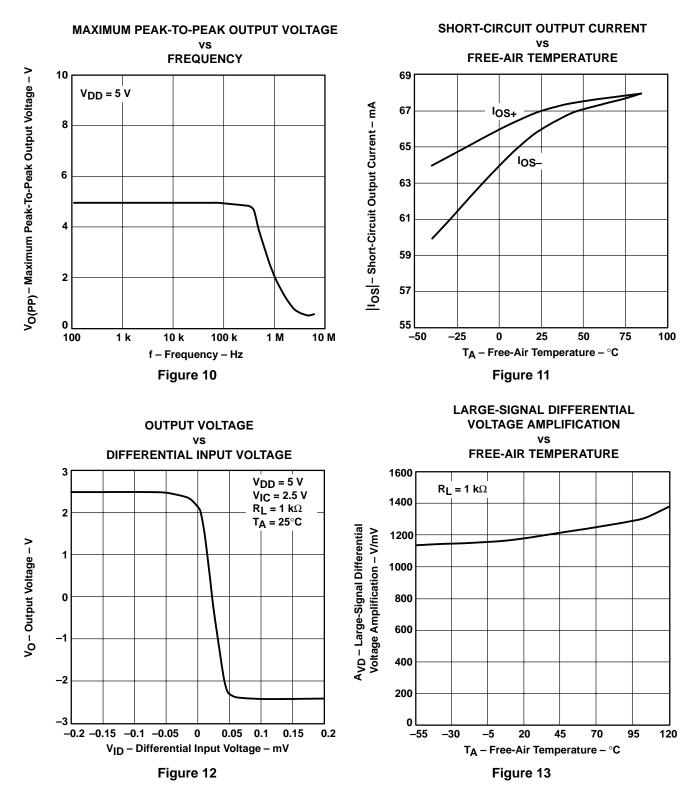








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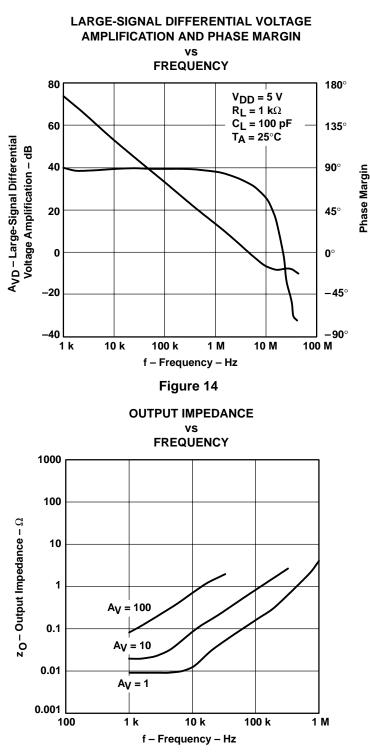
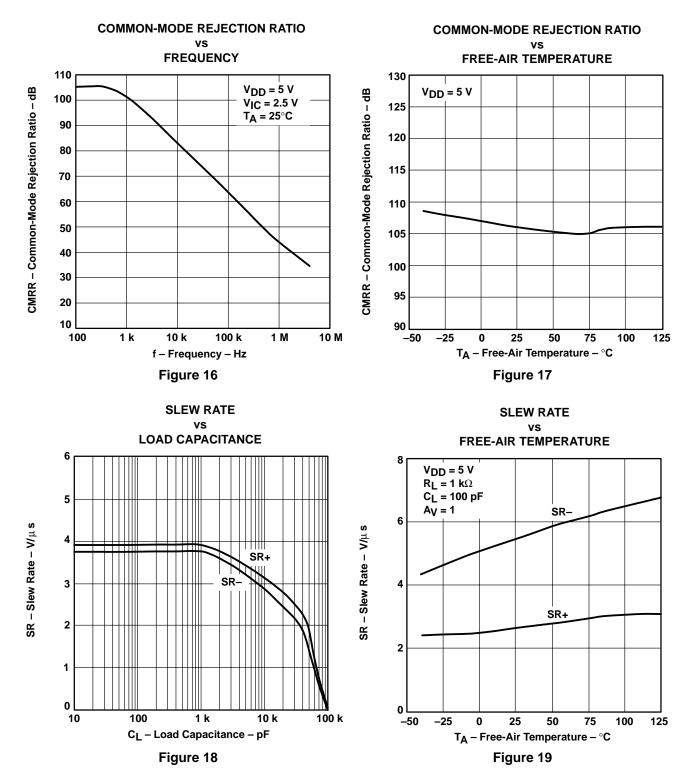


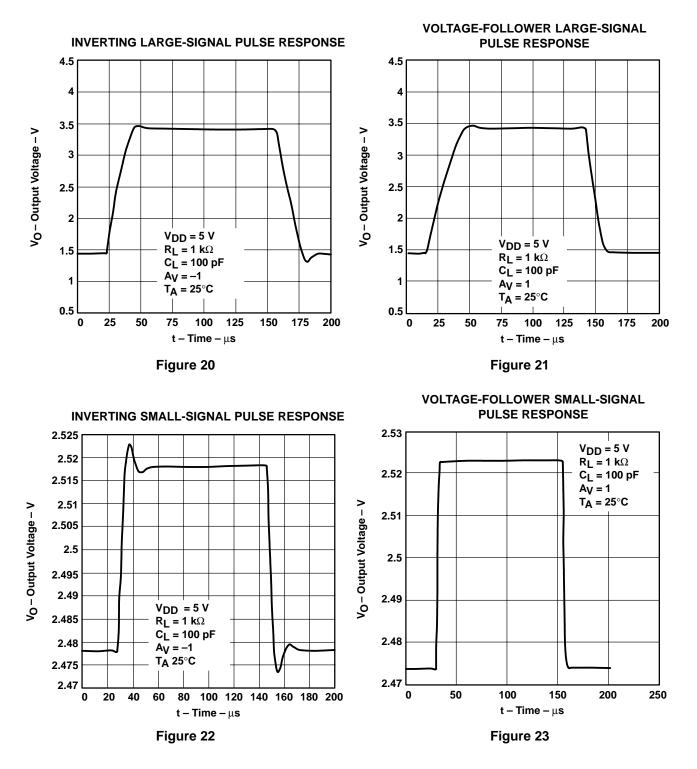
Figure 15



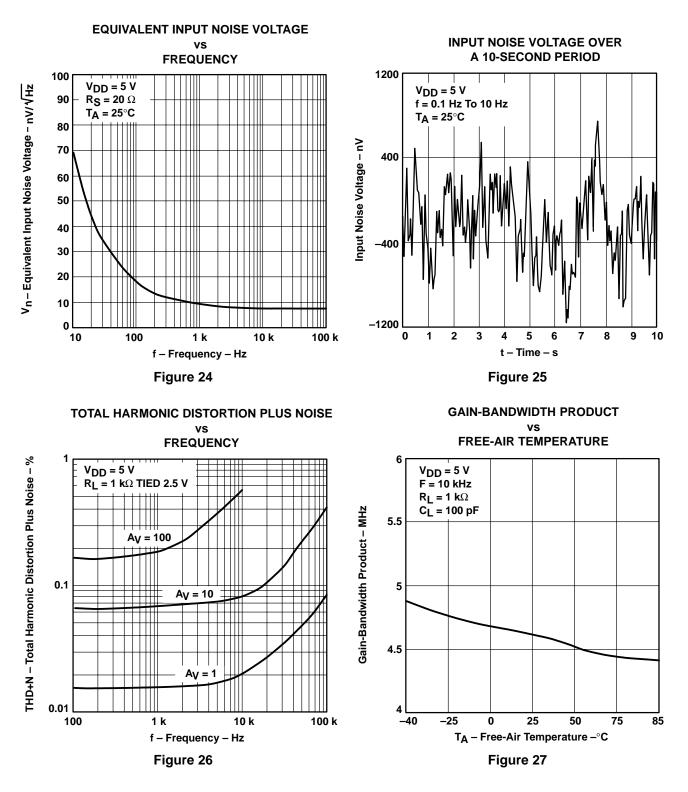
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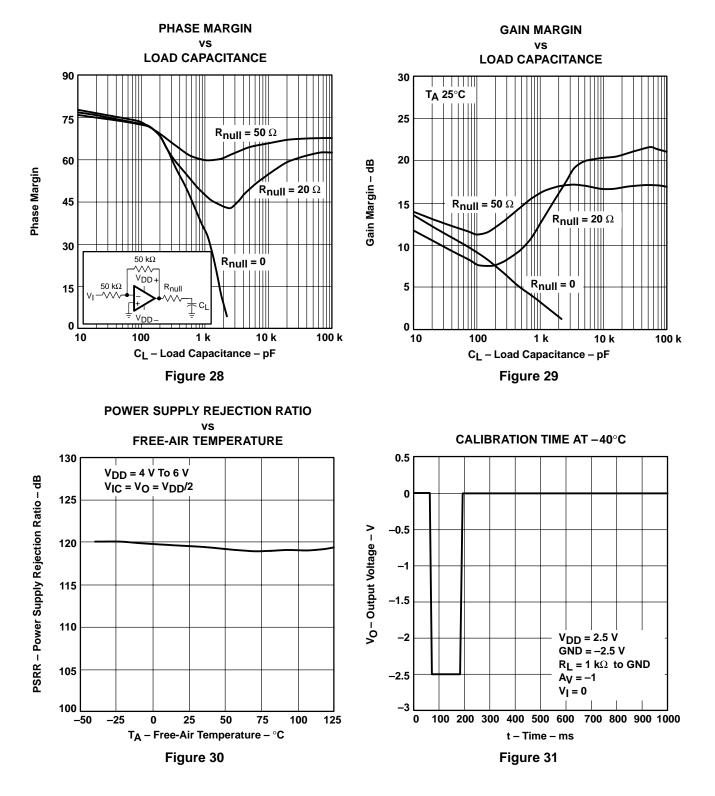














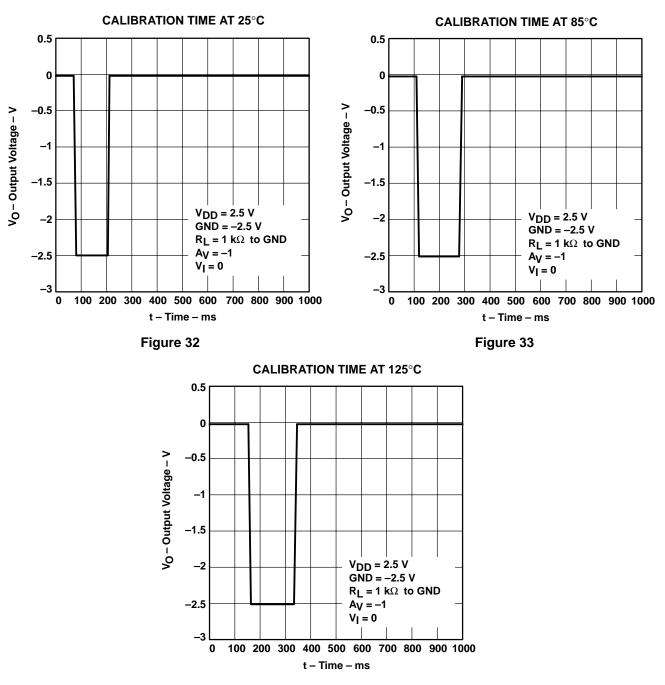


Figure 34



## **APPLICATION INFORMATION**

- The TLC4502 is designed to operate with only a single 5-V power supply, have true differential inputs, and remain in the linear mode with an input common-mode voltage of 0.
- The TLC4502 has a standard dual-amplifier pinout, allowing for easy design upgrades.
- Large differential input voltages can be easily accommodated and, as input differential-voltage protection diodes are not needed, no large input currents result from large differential input voltage. Protection should be provided to prevent the input voltages from going negative more than −0.3 V at 25°C. An input clamp diode with a resistor to the device input terminal can be used for this purpose.
- For ac applications, where the load is capacitively coupled to the output of the amplifier, a resistor can be used from the output of the amplifier to ground. This increases the class-A bias current and prevents crossover distortion. Where the load is directly coupled, for example in dc applications, there is no crossover distortion.
- Capacitive loads, which are applied directly to the output of the amplifier, reduce the loop stability margin. Values of 500 pF can be accommodated using the worst-case noninverting unity-gain connection. Resistive isolation should be considered when larger load capacitance must be driven by the amplifier.

The following typical application circuits emphasize operation on only a single power supply. When complementary power supplies are available, the TLC4502 can be used in all of the standard operational amplifier circuits. In general, introducing a pseudo-ground (a bias voltage of  $V_1/2$  like that generated by the TLE2426) allows operation above and below this value in a single-supply system. Many application circuits shown take advantage of the wide common-mode input-voltage range of the TLC4502, which includes ground. In most cases, input biasing is not required and input voltages that range to ground can easily be accommodated.

#### description of calibration procedure

To achieve high dc gain, large bandwidth, high CMRR and PSRR, as well as good output drive capability, the TLC4502 is built around a 3-stage topology: two gain stages, one rail-to-rail, and a class-AB output stage. A nested Miller topology is used for frequency compensation.

During the calibration procedure, the operational amplifier is removed from the signal path and both inputs are tied to GND. Figure 35 shows a block diagram of the amplifier during calibration mode.



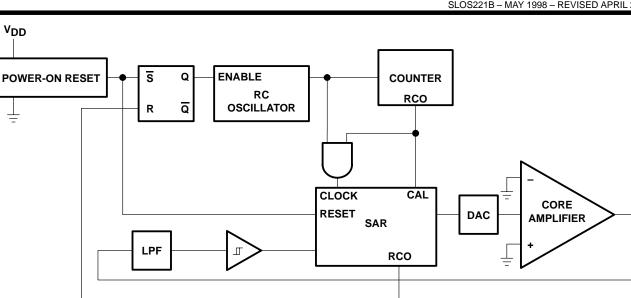


Figure 35. Block Diagram During Calibration Mode

The class AB output stage features rail-to-rail voltage swing and incorporates additional switches to put the output node into a high-impedance mode during the calibration cycle. Small-replica output transistors (matched to the main output transistors) provide the amplifier output signal for the calibration circuit. The TLC4502 also features built-in output short-circuit protection. The output current flowing through the main output transistors is continuously being sensed. If the current through either of these transistors exceeds the preset limit (60 mA – 70 mA) for more than about 1  $\mu$ s, the output transistors are shut down to approximately their quiescent operating point for approximately 5 ms. The device is then returned to normal operation. If the short circuit is still in place, it is detected in less than 1  $\mu$ s and the device is shut down for another 5 ms.

The offset cancellation uses a current-mode digital-to-analog converter (DAC), whose full-scale current allows for an adjustment of approximately  $\pm 5 \text{ mV}$  to the input offset voltage. The digital code producing the cancellation current is stored in the successive-approximation register (SAR).

During power up, when the offset cancellation procedure is initiated, an on-chip RC oscillator is activated to provide the timing of the successive-approximation algorithm. To prevent wide-band noise from interfering with the calibration procedure, an analog low-pass filter followed by a Schmitt trigger is used in the decision chain to implement an averaging process. Once the calibration procedure is complete, the RC oscillator is deactivated to reduce supply current and the associated noise.



## **APPLICATION INFORMATION**

The key operational-amplifier parameters CMRR, PSRR, and offset drift were optimized to achieve superior offset performance. The TLC4502 calibration DAC is implemented by a binary-weighted current array using a pseudo-R-2R MOSFET ladder architecture, which minimizes the silicon area required for the calibration circuitry, and thereby reduces the cost of the TLC4502.

Due to the performance (precision, PSRR, CMRR, gain, output drive, and ac performance) of the TLC4502, it is ideal for applications like:

- Data acquisition systems
- Medical equipment
- Portable digital scales
- Strain gauges
- Automotive sensors
- Digital audio circuits
- Industrial control applications

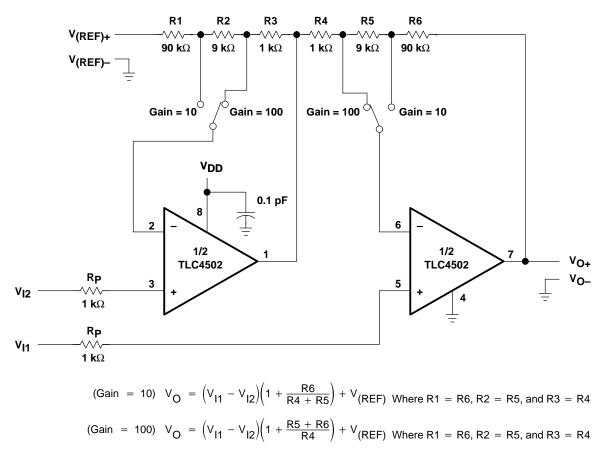
It is also ideal in circuits like:

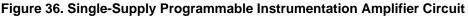
- A precision buffer for current-to-voltage converters, a/d buffers, or bridge applications
- High-impedance buffers or preamplifiers
- Long term integration
- Sample-and-hold circuits
- Peak detectors

The TLC4502 self-calibrating operational amplifier is manufactured using Texas instruments LinEPIC process technology and is available in an 8-pin SOIC (D) Package. The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from -40°C to 125°C. The M-suffix devices are characterized for operation from -55°C to 125°C.



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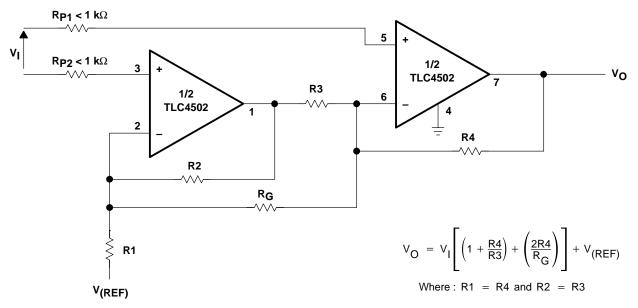
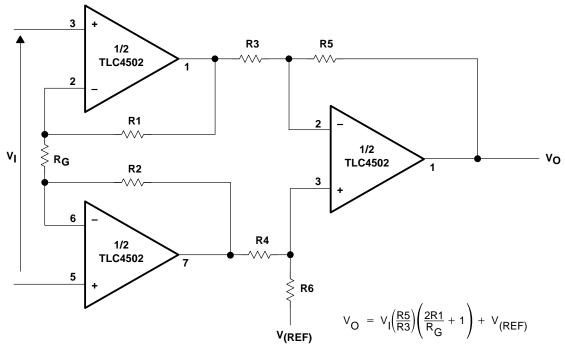


Figure 37. Two Operational-Amplifier Instrumentation Amplifier Circuit



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Where: R1 = R2, R3 = R4, and R5 = R6

Figure 38. Three Operational-Amplifier Instrumentation Amplifier Circuit

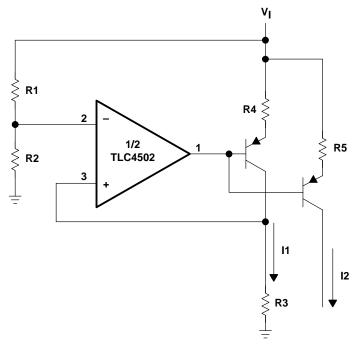


Figure 39. Fixed Current-Source Circuit



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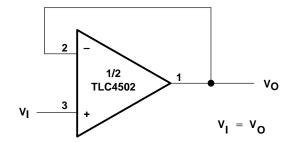


Figure 40. Voltage-Follower Circuit

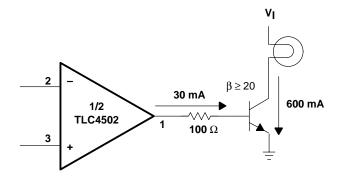


Figure 41. Lamp-Driver Circuit

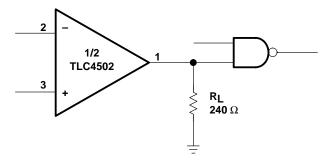
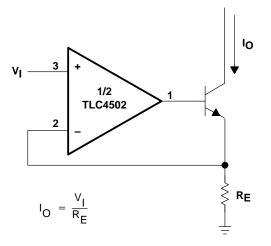


Figure 42. TTL-Driver Circuit







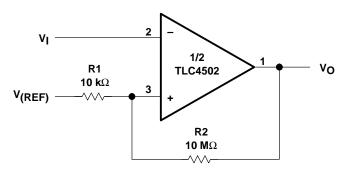


Figure 44. Comparator With Hysteresis Circuit

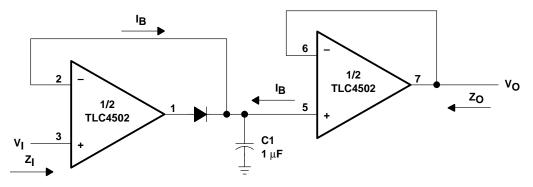


Figure 45. Low-Drift Detector Circuit



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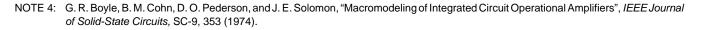
#### macromodel information

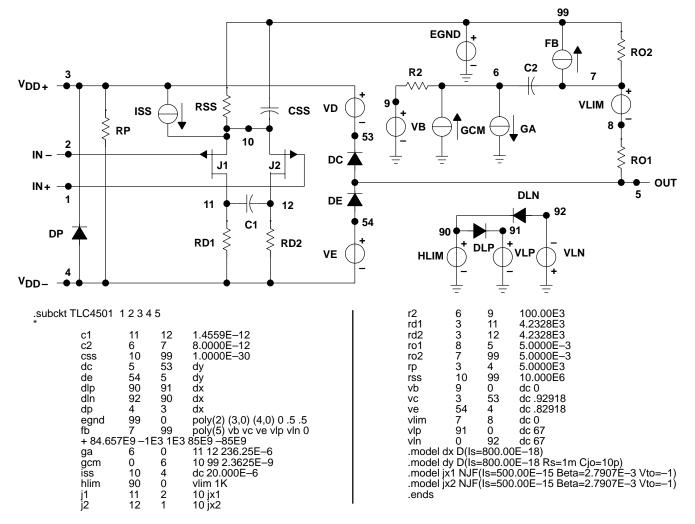
## **APPLICATION INFORMATION**

Macromodel information provided was derived using Microsim Parts™ Release 8, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 4) and subcircuit in Figure 46 are generated using the TLC4501 typical electrical and operating characteristics at T<sub>A</sub> = 25°C. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- ۲ Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate .
- Quiescent power dissipation •
- Input bias current
- Open-loop voltage amplification

- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit





#### Figure 46. Boyle Macromodel and Subcircuit

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## PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	•	Op Temp (°C)	Device Marking	Samples
5962-9753701Q2A	(1) ACTIVE	LCCC	FK	20	1	(2) TBD	POST-PLATE	(3) N / A for Pkg Type	-55 to 125	(4/5) 5962- 9753701Q2A TLC4502 MFKB	Samples
5962-9753701QHA	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753701QHA TLC4502M	Samples
5962-9753701QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753701QPA TLC4502M	Samples
5962-9753702Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9753702Q2A TLC4502 AMFKB	Samples
5962-9753702QHA	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753702QHA TLC4502AM	Samples
5962-9753702QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753702QPA TLC4502AM	Samples
TLC4501ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501AC	Samples
TLC4501ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501AC	Samples
TLC4501AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501AI	Samples
TLC4501AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501AI	Samples
TLC4501AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501AI	Samples
TLC4501AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501AI	Samples
TLC4501AQD	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125		
TLC4501AQDR	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125		
TLC4501CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501C	Samples
TLC4501CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4501C	Samples



## PACKAGE OPTION ADDENDUM

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sampl
TLC4501ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45011	Sampl
TLC4501IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45011	Sampl
TLC4501IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45011	Sampl
TLC4501IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45011	Sampl
TLC4501QD	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125		
TLC4501QDR	PREVIEW	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125		
TLC4502ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AC	Samp
TLC4502ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AC	Samp
TLC4502ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AC	Samp
TLC4502ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AC	Samp
TLC4502AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AI	Samp
TLC4502AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AI	Samp
TLC4502AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AI	Samp
TLC4502AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AI	Samp
TLC4502AMD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	4502AM	Samp
TLC4502AMDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502AM	Samp
TLC4502AMFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9753702Q2A TLC4502 AMFKB	Samp
TLC4502AMJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753702QPA TLC4502AM	Samp



## PACKAGE OPTION ADDENDUM

25-Sep-2013

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	•	Op Temp (°C)	Device Marking	Samp
	(1)					(2)		(3)		(4/5)	
TLC4502AMUB	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753702QHA TLC4502AM	Samp
TLC4502AQD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125	C4502A	
TLC4502AQDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		C4502A	Samp
TLC4502AQDR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125	C4502A	
TLC4502AQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		C4502A	Samp
TLC4502CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502C	Samp
TLC4502CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502C	Samp
TLC4502CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502C	Samp
TLC4502CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502C	Samj
TLC4502ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45021	Samj
TLC4502IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45021	Samj
TLC4502IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45021	Samj
TLC4502IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		45021	Samj
TLC4502MD	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-55 to 125	4502M	
TLC4502MDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		4502M	Samj
TLC4502MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9753701Q2A TLC4502 MFKB	Sam
TLC4502MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	TLC4502MJG	Samj
TLC4502MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753701QPA TLC4502M	Samj
TLC4502MUB	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type	-55 to 125	9753701QHA	Sam



25-Sep-2013

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
										TLC4502M	
TLC4502QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	C4502Q	Samples
TLC4502QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		C4502Q	Samples
TLC4502QDR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125	C4502Q	
TLC4502QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		C4502Q	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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#### OTHER QUALIFIED VERSIONS OF TLC4502, TLC4502A, TLC4502AM, TLC4502M :

- Catalog: TLC4502A, TLC4502
- Military: TLC4502M, TLC4502AM

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION

#### REEL DIMENSIONS

Texas Instruments





TAPE AND REEL INFORMATION

#### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC4501AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC4501IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC4502ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC4502AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC4502CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC4502IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TEXAS INSTRUMENTS

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## PACKAGE MATERIALS INFORMATION

14-Jul-2012



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC4501AIDR	SOIC	D	8	2500	367.0	367.0	35.0
TLC4501IDR	SOIC	D	8	2500	367.0	367.0	35.0
TLC4502ACDR	SOIC	D	8	2500	367.0	367.0	35.0
TLC4502AIDR	SOIC	D	8	2500	367.0	367.0	35.0
TLC4502CDR	SOIC	D	8	2500	367.0	367.0	35.0
TLC4502IDR	SOIC	D	8	2500	367.0	367.0	35.0

## **MECHANICAL DATA**

MCER001A - JANUARY 1995 - REVISED JANUARY 1997



#### **CERAMIC DUAL-IN-LINE**



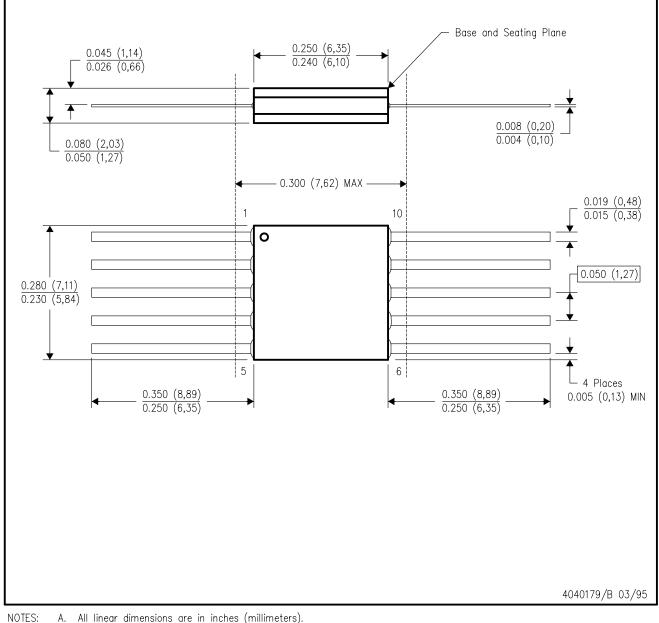
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



- Α. All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice. Β.
  - This package can be hermetically sealed with a ceramic lid using glass frit. C.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. Falls within JEDEC MS-004



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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